

MVP Selecta II

Post Wave and Selective Solder Look Up Automated Optical Inspection Solution

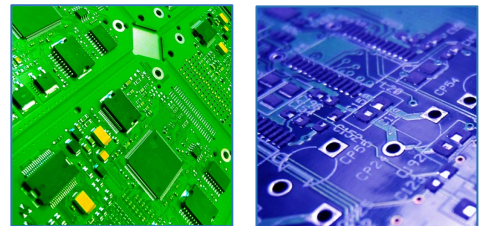


MVP Selecta II

The MVP Selecta II AOI system is designed to complement both wave solder and selective solder processes. Utilizing look up optics, the Selecta II inspects the components soldered by your bottom-side soldering solution. MVP's Selecta II allows for full bottom-side inspection of all wave solder joints including PTH and SMT components in glue. The Selecta II can be used to ensure the quality in your second side process and comes with MVP's ease-of-use programming software.

Key Features

- Full coverage for Wave Solder and Selective Solder Processes
- Full Bottom Side Inspection
- Inspect:
 - Post Wave
 - Post Reflow
 - PTH and
 - SMT Solder Joints
- Fast Easy-To-Use
- Measurement Based AOI
- High Throughput with Proven Reliable Hardware
- 01005 Solder Joint Inspection



Model	Selecta II		
Version	Standard	Duo	
Performance			
Inspection Capability	Paste, Pre-Reflow, Post-Reflow, Post-Wave, Selective Solder, BGA, Metrology based measurement tools		
Programming Speed	Standard SPI and AOI programs are generated in 10-30 mins		
Motion System X and Y	Precision X/Y stage with 0.5 micron positional resolution		
Optical Resolution	Options ² from 5-20um		
Optics			
Optics Camera	25mp		
Optics Illumination	White or Quad Color		
3D Measurement System			
3D Measuring Principle	3D Lighting	Laser Profiler	
3D Speed ¹ (Typical CM ² /s)		16	2.6
3D Sensor X-Y Resolution (um)		12.5	5
3D Sensor Z Repeatability (um) ⁵		0.5	0.4
Max Component Clearance (mm)	35		
Software			
Offline Program Generation	ePro		
Program Debug Environment	iPro and Validate		
SPC and Reporting	AutoData DPC - Sql based data reporting ELSR - End Lot Summary Reporting Optional: AutoData, line integration to paste systems		
CAD and Gerber Inputs	Standard, Placement, Gerber and ODB++ data import		
Defect Review	In-Line or Off-Line defect review using iRepair		
Multi-Pass	Programmable heights and lighting per pass		
Validate ⁷	Automated Program Validation		
System			
Computer	Xeon Processor Based Fast 1TB SSD Hard Drive - 32-256GB Memory		
Operating System	Linux based Multi-Threading Ubuntu Operating System		
Networking	Full network integration (TCP/IP, NFS Protocol)		
Physical			
Inspection Envelope ³	450mm x 400mm ³		
Board Thickness ⁴	0.254 - 12.5mm (0.01 - .5")		
Clearance	Bottom Side to 50.8mm (2")		
Conveyor Height	SMEMA		
Footprint	990mm (39") W x 1100mm (43") D x 1580mm (62") H		
Conveyor Length	996mm (39")		
Power	208-240VAC 50/60Hz, 10A (Optional 110V)		
Air	60 PSI, 1CFM		
Weight ⁶	500 kgs (1100 lbs.)		
Compliance	CE - (UL Optional)		

¹ Using standard resolution, quarter range. Scan speed can be increased using larger profile steps.

² Dependent on camera and lens configurations.

³ Please check final chosen camera configuration, some options can change inspectable area and board size.

⁴ Flex Circuits, Non-Rigid boards will require fixturing. 12.5mm is an advisory for board thickness.

⁵ Static repeatability using MVP calibration target.

⁶ Base Selecta II System

⁷ Program Dependant

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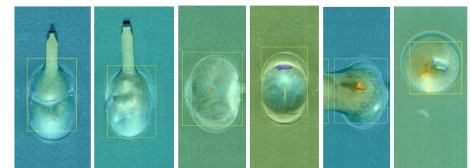
MVP Selecta II

- Comprehensive Defect Coverage
For Your Selective Soldering Process.

MVP has created a new standard for the bottom-side AOI by bringing the key elements of our high performance systems such as structured 3D lighting, flying camera image acquisition, and rule based, library driven inspection software to the MVP Selecta II system. Incorporating the key technical elements of MVP's existing in-line AOI tools, the Selecta II platform offers complete defect coverage, low false calls, and high speed.

Key Features Include:

- **Bottom-Side inspection for PTH Components**
- **Full Solder Joint Inspection and Measurement**
- **Complete Compatibility and Program Portability with MVP's In-Line Inspection Systems**
- **Optimized Price Performance Ratio**
- **MVP's Flying Camera Technology**
- **Inspect Wave, Reflow, PTH and SMT Solder Joints**

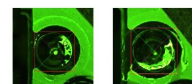


Pin Length

Missing

Bridging

Pin Hole



Solder Coverage